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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f18346t-i-ss

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

PIC16(L)F18326/18346

Pin Diagrams



FIGURE 2: 16-PIN UQFN (4x4)



FIGURE 3: 20-PIN PDIP, SOIC, SSOP



4.1.1.2 Indirect Read with FSR

The program memory can be accessed as data by setting bit 7 of an FSRxH register and reading the matching INDFx register. The MOVIW instruction will place the lower eight bits of the addressed word in the W register. Writes to the program memory cannot be performed via the INDF registers. Instructions that read the program memory via the FSR require one extra instruction cycle to complete. Example 4-2 demonstrates accessing the program memory via an FSR.

The HIGH directive will set bit 7 if a label points to a location in the program memory.

EXAMPLE 4-2: ACCESSING PROGRAM MEMORY VIA FSR

constants			
RETLW	DATA0	;Index0	data
RETLW	DATA1	;Index1	data
RETLW	DATA2		
RETLW	DATA3		
my_functi	on		
; LO	IS OF CODE		
MOVLW	LOW constan	nts	
MOVWF	FSR1L		
MOVLW	HIGH consta	ants	
MOVWF	FSR1H		
MOVIW	0[FSR1]		
; THE PROG	RAM MEMORY IS	S IN W	

4.1.1.3 NVMREG Access

The NVMREG interface allows read/write access to all locations accessible by the FSRs, User ID locations, and EEPROM. The NVMREG interface also provides read-only access to Device ID, Revision ID, and Configuration data. See **Section 11.4** "NVMREG Access" for more information.

4.2 Data Memory Organization

The data memory is partitioned into 32 memory banks with 128 bytes in each bank. Each bank consists of (Figure 4-2):

- 12 core registers
- Special Function Registers (SFR)
- Up to 80 bytes of General Purpose RAM (GPR)
- 16 bytes of common RAM

4.2.1 BANK SELECTION

The active bank is selected by writing the bank number into the Bank Select Register (BSR). Unimplemented memory will read as '0'. All data memory can be accessed either directly (via instructions that use the file registers) or indirectly via the two File Select Registers (FSR). See Section 4.5 "Indirect Addressing" for more information. Data memory uses a 12-bit address. The upper five bits of the address define the Bank address and the lower seven bits select the registers/RAM in that bank.

FIGURE 4-2: BANKED-MEMORY PARTITIONING



4.2.2 CORE REGISTERS

The core registers contain the registers that directly affect basic operation. The core registers occupy the first 12 addresses of every data memory bank (addresses x00h/x80h through x0Bh/x8Bh). These registers are listed below in Table 4-2. For detailed information, see Table 4-4.

TABLE 4-2: CORE REGISTERS

Addresses	BANKx
x00h or x80h	INDF0
x01h or x81h	INDF1
x02h or x82h	PCL
x03h or x83h	STATUS
x04h or x84h	FSR0L
x05h or x85h	FSR0H
x06h or x86h	FSR1L
x07h or x87h	FSR1H
x08h or x88h	BSR
x09h or x89h	WREG
x0Ah or x8Ah	PCLATH
x0Bh or x8Bh	INTCON

8.1 Operation

Interrupts are disabled upon any device Reset. They are enabled by setting the following bits:

- GIE bit of the INTCON register
- Interrupt Enable bit(s) for the specific interrupt event(s)
- PEIE bit of the INTCON register (if the Interrupt Enable bit of the interrupt event is contained in the PIEx registers).

The PIR1, PIR2, PIR3 and PIR4 registers record individual interrupts via interrupt flag bits. Interrupt flag bits will be set, regardless of the status of the GIE, PEIE and individual interrupt enable bits.

The following events happen when an interrupt event occurs while the GIE bit is set:

- Current prefetched instruction is flushed
- · GIE bit is cleared
- Current Program Counter (PC) is pushed onto the stack
- Critical registers are automatically saved to the shadow registers (See "Section 8.5 "Automatic Context Saving")
- PC is loaded with the interrupt vector 0004h

The firmware within the Interrupt Service Routine (ISR) should determine the source of the interrupt by polling the interrupt flag bits. The interrupt flag bits must be cleared before exiting the ISR to avoid repeated interrupts. Because the GIE bit is cleared, any interrupt that occurs while executing the ISR will be recorded through its interrupt flag, but will not cause the processor to redirect to the interrupt vector.

The RETFIE instruction exits the ISR by popping the previous address from the stack, restoring the saved context from the shadow registers and setting the GIE bit.

For additional information on a specific interrupt's operation, refer to its peripheral chapter.

Note 1:	Individual	inte	rrupt	flag	bits	s are	set,
	regardless	of	the	state	of	any	other
	enable bits						

2: All interrupts will be ignored while the GIE bit is cleared. Any interrupt occurring while the GIE bit is clear will be serviced when the GIE bit is set again.

8.2 Interrupt Latency

Interrupt latency is defined as the time from when the interrupt event occurs to the time code execution at the interrupt vector begins. The latency for synchronous interrupts is three or four instruction cycles. The interrupt is sampled during Q1 of the instruction cycle. The actual interrupt latency then depends on the instruction that is executing at the time the interrupt is detected. See Figure 8-2 and Figure 8-3 for more details.

11.0 NONVOLATILE MEMORY (NVM) CONTROL

NVM is separated into two types: Program Flash Memory and Data EEPROM.

NVM is accessible by using both the FSR and INDF registers, or through the NVMREG register interface.

The write time is controlled by an on-chip timer. The write/erase voltages are generated by an on-chip charge pump rated to operate over the operating voltage range of the device.

NVM can be protected in two ways; by either code protection or write protection.

Code protection (CP and CPD bits in Configuration Word 4) disables access, reading and writing, to both the Program Flash Memory and EEPROM via external device programmers. Code protection does not affect the self-write and erase functionality. Code protection can only be Reset by a device programmer performing a Bulk Erase to the device, clearing all nonvolatile memory, Configuration bits, and User IDs.

Write protection prohibits self-write and erase to a portion or all of the Program Flash Memory, as defined by the WRT<1:0> bits of Configuration Word 3. Write protection does not affect a device programmer's ability to read, write, or erase the device.

11.1 Program Flash Memory

Program Flash Memory consists of 16,384 14-bit words as user memory, with additional words for User ID information, Configuration Words, and interrupt vectors. Program Flash Memory provides storage locations for:

- User program instructions
- User defined data

Program Flash Memory data can be read and/or written to through:

- CPU instruction fetch (read-only)
- FSR/INDF indirect access (read-only) (Section 11.3 "FSR and INDF Access")
- NVMREG access (Section 11.4 "NVMREG Access"
- In-Circuit Serial Programming[™] (ICSP[™])

Read operations return a single word of memory. When write and erase operations are done on a row basis, the row size is defined in Table 11-1. Program Flash Memory will erase to a logic '1' and program to a logic '0'.

TABLE 11-1: FLASH MEMORY ORGANIZATION BY DEVICE

Device	Row Erase (words)	Write Latches (words)	
PIC16(L)F18326	22	20	
PIC16(L)F18346	52	52	

It is important to understand the Program Flash Memory structure for erase and programming operations. Program Flash Memory is arranged in rows. A row consists of 32 14-bit program memory words. A row is the minimum size that can be erased by user software.

All or a portion of a row can be programmed. Data to be written into the program memory row is written to 14-bit wide data write latches. These latches are not directly accessible to the user, but may be loaded via sequential writes to the NVMDATH:NVMDATL register pair.

Note:	To modify only a portion of a previously							
	programmed row, then the contents of the							
	entire row must be read and saved in							
	RAM prior to the erase. Then, the new							
	data and retained data can be written into							
	the write latches to reprogram the row of							
	Program Flash Memory. Any							
	unprogrammed locations can be written							
	without first erasing the row. In this case,							
	it is not necessary to save and rewrite the							
	other previously programmed locations							

11.1.1 PROGRAM MEMORY VOLTAGES

The Program Flash Memory is readable and writable during normal operation over the full VDD range.

11.1.1.1 Programming Externally

The program memory cell and control logic support write and Bulk Erase operations down to the minimum device operating voltage.

11.1.1.2 Self-Programming

The program memory cell and control logic will support write and row erase operations across the entire VDD range. Bulk Erase is not supported when self-programming.





R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	U-0	U-0	U-0	U-0	
LATB7	LATB6	LATB5	LATB4	—	—	—	—	
bit 7							bit 0	
Legend:								
R = Readable	R = Readable bit W = Writable bit			U = Unimplemented bit, read as '0'				
u = Bit is uncha	a = Bit is unchanged x = Bit is unknown			-n/n = Value at POR and BOR/Value at all other Resets				
'1' = Bit is set		'0' = Bit is clea	ared					

REGISTER 12-11: LATB: PORTB DATA LATCH REGISTER

bit 7-4 LATB<7:4>: RB<5:4> Output Latch Value bits⁽¹⁾

bit 3-0 Unimplemented: Read as '0'

Note 1: Writes to LATB are equivalent with writes to the corresponding PORTB register.Reads from LATB register return register values, not I/O pin values.

REGISTER 12-12: ANSELB: PORTB ANALOG SELECT REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	U-0	U-0	U-0	U-0
ANSB7	ANSB6	ANSB5	ANSB4	—	_	_	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **ANSB<7:4>**: Analog Select between Analog or Digital Function

1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.

0 = Digital I/O. Pin is assigned to port or digital special function.

bit 3-0 Unimplemented: Read as '0'

Note 1: Setting ANSB[n] = 1 disables the digital input circuitry. Weak pull-ups, if available, are unaffected. The corresponding TRIS bit must be set to Input mode by the user to allow external control of the voltage on the pin.

16.0 FIXED VOLTAGE REFERENCE (FVR)

The Fixed Voltage Reference, or FVR, is a stable voltage reference, independent of VDD, with 1.024V, 2.048V or 4.096V selectable output levels. The output of the FVR subsystem can be configured to supply a reference voltage to the following:

- · ADC input channel
- ADC positive reference
- Comparator positive input
- Digital-to-Analog Converter (DAC)

The FVR can be enabled by setting the FVREN bit of the FVRCON register.

Note: Fixed Voltage Reference output cannot exceed VDD.

16.1 Independent Gain Amplifiers

The output of the FVR, which is supplied to the ADC, Comparators and DAC, is routed through two independent programmable gain amplifiers. Each amplifier can be programmed for a gain of 1x, 2x or 4x, to produce the three possible voltage levels.

The ADFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the ADC module. Reference Section 22.0 "Analog-to-Digital Converter (ADC) Module" for additional information.

The CDAFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the DAC and comparator module. Reference Section 24.0 "5-bit Digital-to-Analog Converter (DAC1) Module" and Section 18.0 "Comparator Module" for additional information.

16.2 FVR Stabilization Period

When the Fixed Voltage Reference module is enabled, it requires time for the reference and amplifier circuits to stabilize. See Table 35-16 for FVR start-up times.

FIGURE 16-1: VOLTAGE REFERENCE BLOCK DIAGRAM



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17.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 μs after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed.

TABLE 17-2: SUMMARY OF REGISTERS ASSOCIATED WITH THE TEMPERATURE INDICATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFV	R<1:0>	180

Legend: Shaded cells are unused by the temperature indicator module.

R/W-0/	0 R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
OVRE	OVRC	OVRB	OVRA	STRD ⁽²⁾	STRC ⁽²⁾	STRB ⁽²⁾	STRA ⁽²⁾
bit 7							bit 0
Legend:							
R = Read	able bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'	
u = Bit is u	unchanged	x = Bit is unkr	nown	-n/n = Value	at POR and BO	R/Value at all c	other Resets
'1' = Bit is	set	'0' = Bit is cle	ared	q = Value de	pends on condit	ion	
bit 7	OVRD: Stee	ring Data D bit					
bit 6	OVRC: Stee	ring Data C bit					
bit 5	OVRB: Stee	ring Data B bit					
bit 4	OVRA: Stee	ring Data A bit					
bit 3	STRD: Steer	ring Enable bit [)(2)				
	1 = CWGxD	output has the	CWGx data in	put waveform v	vith polarity con	trol from POLD	bit
	0 = CWGxD	output is assigr	ned to value of	OVRD bit			
bit 2	STRC: Steer	ring Enable bit C	(2)				
	1 = CWGxC	output has the	CWGx data in	put waveform v	vith polarity con	trol from POLC	bit
	0 = CWGxC	output is assigr	ned to value of	OVRC bit			
bit 1	STRB: Steer	ring Enable bit E	3(2)				
	1 = CWGxB	output has the	CWGx data inp	out waveform v	with polarity con	trol from POLB	bit
	0 = CWGxB	output is assign	ied to value of	OVRB bit			
bit 0	STRA: Steer	ring Enable bit A					
	1 = CWGxA	output has the	CWGx data inj	out waveform v	with polarity con	trol from POLA	bit
	0 = CVVGxA	output is assign	ied to value of	OVRA bit			
Note 1:	The bits in this reg	gister apply only	/ when MODE	<2:0> = 00x (F	Register 20-1, st	eering modes)	

REGISTER 20-5: CWGxSTR⁽¹⁾: CWG STEERING CONTROL REGISTER

2: This bit is double-buffered when MODE < 2:0 > = 0.01.

21.2 CLCx Interrupts

An interrupt will be generated upon a change in the output value of the CLCx when the appropriate interrupt enables are set. A rising edge detector and a falling edge detector are present in each CLC for this purpose.

The CLCxIF bit of the associated PIR3 register will be set when either edge detector is triggered and its associated enable bit is set. The LCxINTP bit enables rising edge interrupts and the LCxINTN bit enables falling edge interrupts. Both are located in the CLCxCON register.

To fully enable the interrupt, set the following bits:

- CLCxIE bit of the PIE3 register
- LCxINTP bit of the CLCxCON register (for a rising edge detection)
- LCxINTN bit of the CLCxCON register (for a falling edge detection)
- PEIE and GIE bits of the INTCON register

The CLCxIF bit of the PIR3 register, must be cleared in software as part of the interrupt service. If another edge is detected while this flag is being cleared, the flag will still be set at the end of the sequence.

21.3 Output Mirror Copies

Mirror copies of all LCxCON output bits are contained in the CLCDATA register. Reading this register samples the outputs of all CLCs simultaneously. This prevents any timing skew introduced by testing or reading the LCxOUT bits in the individual CLCxCON registers.

21.4 Effects of a Reset

The CLCxCON register is cleared to zero as the result of a Reset. All other selection and gating values remain unchanged.

21.5 Operation During Sleep

The CLC module operates independently from the system clock and will continue to run during Sleep, provided that the input sources selected remain active.

The HFINTOSC remains active during Sleep when the CLC module is enabled and the HFINTOSC is selected as an input source, regardless of the system clock source selected.

In other words, if the HFINTOSC is simultaneously selected as the system clock and as a CLC input source, when the CLC is enabled, the CPU will go idle during Sleep, but the CLC will continue to operate and the HFINTOSC will remain active.

This will have a direct effect on the Sleep mode current.

21.6 CLCx Setup Steps

The following steps will be followed when setting up the CLCx:

- Disable CLCx by clearing the LCxEN bit.
- Select desired inputs using CLCxSEL0 through CLCxSEL3 registers (See Table 21-1).
- · Clear any associated ANSEL bits.
- Set all TRIS bits associated with external CLC inputs.
- Enable the chosen inputs through the four gates using CLCxGLS0, CLCxGLS1, CLCxGLS2, and CLCxGLS3 registers.
- Select the gate output polarities with the LCxGyPOL bits of the CLCxPOL register.
- Select the desired logic function with the LCxMODE<2:0> bits of the CLCxCON register.
- Select the desired polarity of the logic output with the LCxPOL bit of the CLCxPOL register. (This step may be combined with the previous gate output polarity step).
- If driving a device pin, set the desired pin PPS control register and also clear the TRIS bit corresponding to that output.
- If interrupts are desired, configure the following bits:
 - Set the LCxINTP bit in the CLCxCON register for rising event.
 - Set the LCxINTN bit in the CLCxCON register for falling event.
 - Set the CLCxIE bit of the PIE3 register.
 - Set the GIE and PEIE bits of the INTCON register.
- Enable the CLCx by setting the LCxEN bit of the CLCxCON register.

U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
	_	_	_		MDMS	S<3:0>	
bit 7	·						bit 0
1							
Legend:							
R = Readabl	le bit	W = Writable	bit	U = Unimpler	nented bit, read	l as '0'	
u = Bit is und	changed	x = Bit is unkr	nown	-n/n = Value a	at POR and BO	R/Value at all c	other Resets
'1' = Bit is se	et	'0' = Bit is clea	ared				
L							
bit 7-4	Unimplemen	ted: Read as '	0'				
bit 3-0	MDMS<3:0>	Modulation So	urce Selectio	n bits			
	1111 = CIC						
	1110 = CLC						
	1101 = CLC						
	1100 = CLC						
	1011 = NCC)1 output					
	1010 = FUS	ART1 TX outp	ut				
	1001 = MSS	SP2 SDO2 outr	out				
	1000 = MSS	SP1 SDO1 outp	out				
	0111 = C2 (Comparator 2)	output				
	0110 = C1 (Comparator 1)	output				
	0101 = PWN	vic victor victo					
	0100 = PWN	M5 output					
	0011 = CCP	2 output (PWN	1 Output mod	le only)			
	0010 = CCP	1 output (PWN	1 Output mod	le only)			
	0001 = MDN	MINPPS	-				
	0000 = MDE	BIT bit of MDCO	ON register is	modulation sou	Jrce		

REGISTER 25-2: MDSRC: MODULATION SOURCE CONTROL REGISTER

REGISTER 27-3: TMRxL⁽¹⁾: TIMERx LOW BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
			TMRx	L<7:0>			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	nented bit, rea	d as '0'	
u = Bit is uncha	anged	x = Bit is unkn	nown	-n/n = Value a	at POR and BC	R/Value at all	other Resets
'1' = Bit is set		'0' = Bit is clea	ared				

bit 7-0 TMRxL<7:0>: TMRx Low Byte bits

Note 1: 'x' refers to either '1', '3' or '5' for the respective Timer1/3/5 registers.

REGISTER 27-4: TMRxH⁽¹⁾: TIMERx HIGH BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
			TMRxH	H<7:0>			
bit 7							bit 0
L a manual.							

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 TMRxH<7:0>: TMRx High Byte bits

Note 1: 'x' refers to either '1', '3' or '5' for the respective Timer1/3/5 registers.

29.0 CAPTURE/COMPARE/PWM MODULES

The Capture/Compare/PWM module is a peripheral that allows the user to time and control different events and to generate Pulse-Width Modulation (PWM) signals. In Capture mode, the peripheral allows the timing of the duration of an event. The Compare mode allows the user to trigger an external event when a predetermined amount of time has expired. The PWM mode can generate Pulse-Width Modulated signals of varying frequency and duty cycle.

This family of devices contains four standard Capture/Compare/PWM modules (CCP1, CCP2, CCP3 and CCP4).

The Capture and Compare functions are identical for all CCP modules.

29.1 CCP/PWM Clock Selection

The PIC16(L)F18326/18346 devices allow each individual CCP and PWM module to select the timer source that controls the module. Each module has an independent selection.

As there are up to three 8-bit timers with auto-reload (Timer2, Timer4, and Timer6), PWM mode on the CCP and PWM modules can use any of these timers.

The CCPTMRS register is used to select which timer is used.

- Note 1: In devices with more than one CCP module, it is very important to pay close attention to the register names used. A number placed after the module acronym is used to distinguish between separate modules. For example, the CCP1CON and CCP2CON control the same operational aspects of two completely different CCP modules.
 - 2: Throughout this section, generic references to a CCP module in any of its operating modes may be interpreted as being equally applicable to CCPx module. Register names, module signals, I/O pins, and bit names may use the generic designator 'x' to indicate the use of a numeral to distinguish a particular module, when required.

29.2 Capture Mode

Capture mode makes use of either the 16-bit Timer0 or Timer1 resource. When an event occurs on the capture source, the 16-bit CCPRxH:CCPRxL register pair captures and stores the 16-bit value of the TMR0H:TMR0L or TMR1H:TMR1L register pair, respectively. An event is defined as one of the following and is configured by the CCPxMODE<3:0> bits of the CCPxCON register:

- · Every falling edge
- Every rising edge
- Every 4th rising edge
- Every 16th rising edge

When a capture is made, the Interrupt Request Flag bit CCPxIF of the PIR4 register is set. The interrupt flag must be cleared in software. If another capture occurs before the value in the CCPRxH, CCPRxL register pair is read, the old captured value is overwritten by the new captured value.

Figure 29-1 shows a simplified diagram of the capture operation.

29.2.1 CAPTURE SOURCES

In Capture mode, the CCPx pin should be configured as an input by setting the associated TRIS control bit.

Note: If the CCPx pin is configured as an output, a write to the port can cause a Capture condition.

The capture source is selected by configuring the CCPxCTS<3:0> bits of the CCPxCAP register. The following sources can be selected:

- · CCPxPPS input
- C1 output
- C2_output
- NCO_output
- IOC_interrupt
- LC1_output
- LC2_output
- LC3_output
- LC4_output





30.2.1 SPI MODE REGISTERS

The MSSPx module has five registers for SPI mode operation. These are:

- MSSPx STATUS register (SSPxSTAT)
- MSSPx Control register 1 (SSPxCON1)
- MSSPx Control register 3 (SSPxCON3)
- MSSPx Data Buffer register (SSPxBUF)
- MSSPx Address register (SSPxADD)
- MSSPx Shift register (SSPxSR)
- (Not directly accessible)

SSPxCON1 and SSPSTAT are the control and STATUS registers in SPI mode operation. The SSPxCON1 register is readable and writable. The lower six bits of the SSPxSTAT are read-only. The upper two bits of the SSPxSTAT are read/write.

In one SPI Master mode, SSPxADD can be loaded with a value used in the Baud Rate Generator. More information on the Baud Rate Generator is available in Section 30.7 "Baud Rate Generator".

SSPxSR is the shift register used for shifting data in and out. SSPxBUF provides indirect access to the SSPxSR register. SSPxBUF is the buffer register to which data bytes are written, and from which data bytes are read.

In receive operations, SSPxSR and SSPxBUF together create a buffered receiver. When SSPxSR receives a complete byte, it is transferred to SSPxBUF and the SSPxIF interrupt is set.

During transmission, the SSPxBUF is not buffered. A write to SSPxBUF will write to both SSPxBUF and SSPxSR.

30.2.2 SPI MODE OPERATION

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits (SSPxCON1<5:0> and SSPxSTAT<7:6>). These control bits allow the following to be specified:

- Master mode (SCK is the clock output)
- Slave mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Data Input Sample Phase (middle or end of data output time)
- Clock Edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select mode (Slave mode only)

To enable the serial port, SSP Enable bit, SSPEN of the SSPxCON1 register, must be set. To reset or reconfigure SPI mode, clear the SSPEN bit, re-initialize the SSPxCONy registers and then set the SSPEN bit. This configures the SDI, SDO, SCK and SS pins as serial port pins. For the pins to behave as the serial port function, some must have their data direction bits (in the TRIS register) appropriately programmed as follows:

- SDI must have corresponding TRIS bit set
- SDO must have corresponding TRIS bit cleared
 SCK (Master mode) must have corresponding
- TRIS bit cleared
- SCK (Slave mode) must have corresponding <u>TRIS</u> bit set
- SS must have corresponding TRIS bit set

Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value.



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31.3.2 AUTO-BAUD OVERFLOW

During the course of automatic-baud detection, the ABDOVF bit of the BAUDxCON register will be set if the baud rate counter overflows before the fifth rising edge is detected on the RX pin. The ABDOVF bit indicates that the counter has exceeded the maximum count that can fit in the 16 bits of the SPxBRGH:SPxBRGL register pair. The Overflow condition will set the RCIF flag. The counter continues to count until the fifth rising edge is detected on the RX pin. The RCIDL bit will remain false ('0') until the fifth rising edge at which time the RCIDL bit will be set. If the RCREG is read after the overflow occurs but before the fifth rising edge, then the fifth rising edge will set the RCIF again.

Terminating the auto-baud process early to clear an Overflow condition will prevent proper detection of the sync character fifth rising edge. If any falling edges of the sync character have not yet occurred when the ABDEN bit is cleared, then those will be falsely detected as Start bits. The following steps are recommended to clear the Overflow condition:

- 1. Read RCREG to clear RCIF
- 2. If RCIDL is zero, then wait for RCIF and repeat step 1
- 3. Clear the ABDOVF bit

31.3.3 AUTO-WAKE-UP ON BREAK

During Sleep mode, all clocks to the EUSART1 are suspended. Because of this, the Baud Rate Generator is inactive and a proper character reception cannot be performed. The Auto-Wake-up feature allows the controller to wake-up due to activity on the RX/DT line. This feature is available only in Asynchronous mode.

The Auto-Wake-up feature is enabled by setting the WUE bit of the BAUD1CON register. Once set, the normal receive sequence on RX/DT is disabled, and the EUSART1 remains in an Idle state, monitoring for a wake-up event independent of the CPU mode. A wake-up event consists of a high-to-low transition on the RX/DT line. (This coincides with the start of a Sync Break or a wake-up signal character for the LIN protocol.)

The EUSART1 module generates an RCIF interrupt coincident with the wake-up event. The interrupt is generated synchronously to the Q clocks in normal CPU operating modes (Figure 31-7), and asynchronously if the device is in Sleep mode (Figure 31-8). The Interrupt condition is cleared by reading the RC1REG register.

The WUE bit is automatically cleared by the low-to-high transition on the RX line at the end of the Break. This signals to the user that the Break event is over. At this point, the EUSART1 module is in Idle mode waiting to receive the next character.

31.3.3.1 Special Considerations

Break Character

To avoid character errors or character fragments during a wake-up event, the wake-up character must be all zeros.

When the wake-up is enabled the function works independent of the low time on the data stream. If the WUE bit is set and a valid non-zero character is received, the low time from the Start bit to the first rising edge will be interpreted as the wake-up event. The remaining bits in the character will be received as a fragmented character and subsequent characters can result in framing or overrun errors.

Therefore, the initial character in the transmission must be all '0's. This must be ten or more bit times, 13-bit times recommended for LIN bus, or any number of bit times for standard RS-232 devices.

Oscillator Start-up Time

Oscillator start-up time must be considered, especially in applications using oscillators with longer start-up intervals (i.e., LP, XT or HS/PLL mode). The Sync Break (or wake-up signal) character must be of sufficient length, and be followed by a sufficient interval, to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART1.

WUE Bit

The wake-up event causes a receive interrupt by setting the RCIF bit. The WUE bit is cleared in hardware by a rising edge on RX/DT. The Interrupt condition is then cleared in software by reading the RC1REG register and discarding its contents.

To ensure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process before setting the WUE bit. If a receive operation is not occurring, the WUE bit may then be set just prior to entering the Sleep mode.

TABLE 35-22: SPI MODE CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	Symbol	Characteristic	Min.	Тур.†	Max.	Units	Conditions
SP70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK \downarrow or SCK \uparrow input	2.25*Tcy	—	_	ns	
SP71*	TscH	SCK input high time (Slave mode)	Tcy + 20	—		ns	\land
SP72*	TscL	SCK input low time (Slave mode)	Tcy + 20	—	_	ns	
SP73*	TDIV2scH, TDIV2scL	Setup time of SDI data input to SCK edge	100	—	_	ns _	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—		ns	
SP75*	TDOR	SDO data output rise time		10	25 <	ns	3.0∀ ≤ V DD ≤ 5.5V
				25	50	nş	1.8∀ ≤ VDD ≤ 5.5V
SP76*	TDOF	SDO data output fall time	—	10	25	ns	
SP77*	TssH2doZ	SS↑ to SDO output high-impedance	10	<u> </u>	-50	ns	
SP78*	TscR	SCK output rise time	—	10	25	ns	$3.0V \le V\text{DD} \le 5.5V$
		(Master mode)	—	25	50	ns	$1.8V \leq V\text{DD} \leq 5.5V$
SP79*	TscF	SCK output fall time (Master mode)	\prec	10 \	25	ns	
SP80*	TscH2doV,	SDO data output valid after SCK	\		√50	ns	$3.0V \leq V\text{DD} \leq 5.5V$
	TscL2doV	edge		$\rightarrow \rightarrow$	145	ns	$1.8V \leq V\text{DD} \leq 5.5V$
SP81*	TDOV2scH, TDOV2scL	SDO data output setup to SCK edge	4 Tcy		_	ns	
SP82*	TssL2doV	SDO data output valid after SS edge		_	50	ns	
SP83*	TscH2ssH, TscL2ssH	SS ↑ after SCK edge	1.5 TCY + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ." column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Ν	ILLIMETER	S			
Dim	ension Limits	MIN	NOM	MAX		
Contact Pitch	E		1.27 BSC			
Contact Pad Spacing	С		5.40			
Contact Pad Width	X			0.60		
Contact Pad Length	Y			1.50		
Distance Between Pads	Gx	0.67				
Distance Between Pads	G	3.90				

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2065A

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (04/2016)

Initial release of the document.

Revision B (04/2017)

Updated pin diagrams; Minor corrections to Table 1-1; Added "Guidelines for Getting Started With PIC16(L)F183XX" chapter; updated Figure 2-1; Added section 4.1.1.3 NVMREG Access; Section 4.2.1. BANK SELECTION; Updated ADACT Register; Added new Figure 4-8; Section 4.5.4 DATA EEPROM MEMORY; Updated Figure 18-2; Minor changes to all chapters.